

# PDTA123YT

PNP resistor-equipped transistor; R1 = 2.2 k $\Omega$ , R2 = 10 k $\Omega$

Rev. 02 — 11 June 2004

Objective data

## 1. Product profile

### 1.1 General description

PNP resistor-equipped transistor. NPN complement: PDTC123YT.

### 1.2 Features

- Built-in bias resistors
- Simplifies circuit design
- Reduces component count
- Reduces pick and place costs.

### 1.3 Applications

- General-purpose switching and amplification
- Inverter and interface circuits
- Circuit driver.

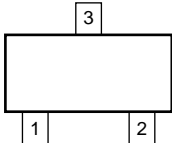
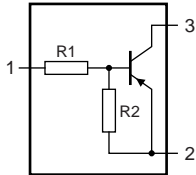
### 1.4 Quick reference data

Table 1: Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V <sub>CEO</sub>	collector-emitter voltage		-	-	-50	V
I <sub>O</sub>	output current (DC)		-	-	-100	mA
R1	bias resistor		-	2.2	-	k $\Omega$
R2	bias resistor		-	10	-	k $\Omega$

## 2. Pinning information

Table 2: Discrete pinning

Pin	Description	Simplified outline	Symbol
1	base		
2	emitter		
3	collector		

SOT23

sym003

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### 3. Ordering information

Table 3: Ordering information

Type number	Package		
	Name	Description	Version
PDTA123YT	-	plastic surface mounted package; 3 leads	SOT23

### 4. Marking

Table 4: Marking

Type number	Marking code <sup>[1]</sup>
PDTA123YT	*AD

- [1] \* = p: made in Hong Kong.  
 \* = t: made in Malaysia.  
 \* = W: made in China.

### 5. Limiting values

Table 5: Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CBO}$	collector-base voltage	open emitter	-	-50	V
$V_{CEO}$	collector-emitter voltage	open base	-	-50	V
$V_{EBO}$	emitter-base voltage	open collector	-	-5	V
$V_I$	input voltage				
	positive		-	+5	V
	negative		-	-12	V
$I_O$	output current (DC)		-	-100	mA
$I_{CM}$	peak collector current		-	-100	mA
$P_{tot}$	total power dissipation	$T_{amb} \leq 25\text{ °C}$ <sup>[1]</sup>	-	250	mW
$T_{stg}$	storage temperature		-65	+150	°C
$T_j$	junction temperature		-	150	°C
$T_{amb}$	operating ambient temperature		-65	+150	°C

- [1] Refer to standard mounting conditions.

### 6. Thermal characteristics

Table 6: Thermal characteristics

Symbol	Parameter	Conditions	Value	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	<sup>[1]</sup> 500	K/W

- [1] Refer to standard mounting conditions.

## 7. Characteristics

**Table 7: Characteristics**

$T_{amb} = 25\text{ }^{\circ}\text{C}$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{CBO}$	collector-base cut-off current	$V_{CB} = -50\text{ V}$ ; $I_E = 0\text{ A}$	-	-	-100	nA
$I_{CEO}$	collector-emitter cut-off current	$V_{CE} = -30\text{ V}$ ; $I_B = 0\text{ A}$	-	-	-1	$\mu\text{A}$
		$V_{CE} = -30\text{ V}$ ; $I_B = 0\text{ A}$ ; $T_j = 150\text{ }^{\circ}\text{C}$	-	-	-50	$\mu\text{A}$
$I_{EBO}$	emitter-base cut-off current	$V_{EB} = -5\text{ V}$ ; $I_C = 0\text{ A}$	-	-	-700	$\mu\text{A}$
$h_{FE}$	DC current gain	$V_{CE} = -5\text{ V}$ ; $I_C = -5\text{ mA}$	35	-	-	
$V_{CEsat}$	collector-emitter saturation voltage	$I_C = -10\text{ mA}$ ; $I_B = -0.5\text{ mA}$	-	-	-150	mV
$V_{i(off)}$	input-off voltage	$V_{CE} = -5\text{ V}$ ; $I_C = -100\text{ }\mu\text{A}$	-	-0.75	-0.3	V
$V_{i(on)}$	input-on voltage	$V_{CE} = -300\text{ mV}$ ; $I_C = -20\text{ mA}$	-2.5	-1.15	-	V
R1	input resistor		1.54	2.2	2.86	k $\Omega$
$R2/R1$	resistor ratio		3.6	4.5	5.5	
$C_c$	collector capacitance	$V_{CB} = -10\text{ V}$ ; $I_E = I_e = 0\text{ A}$ ; $f = 1\text{ MHz}$	-	-	2	pF

8. Package outline

Plastic surface mounted package; 3 leads

SOT23

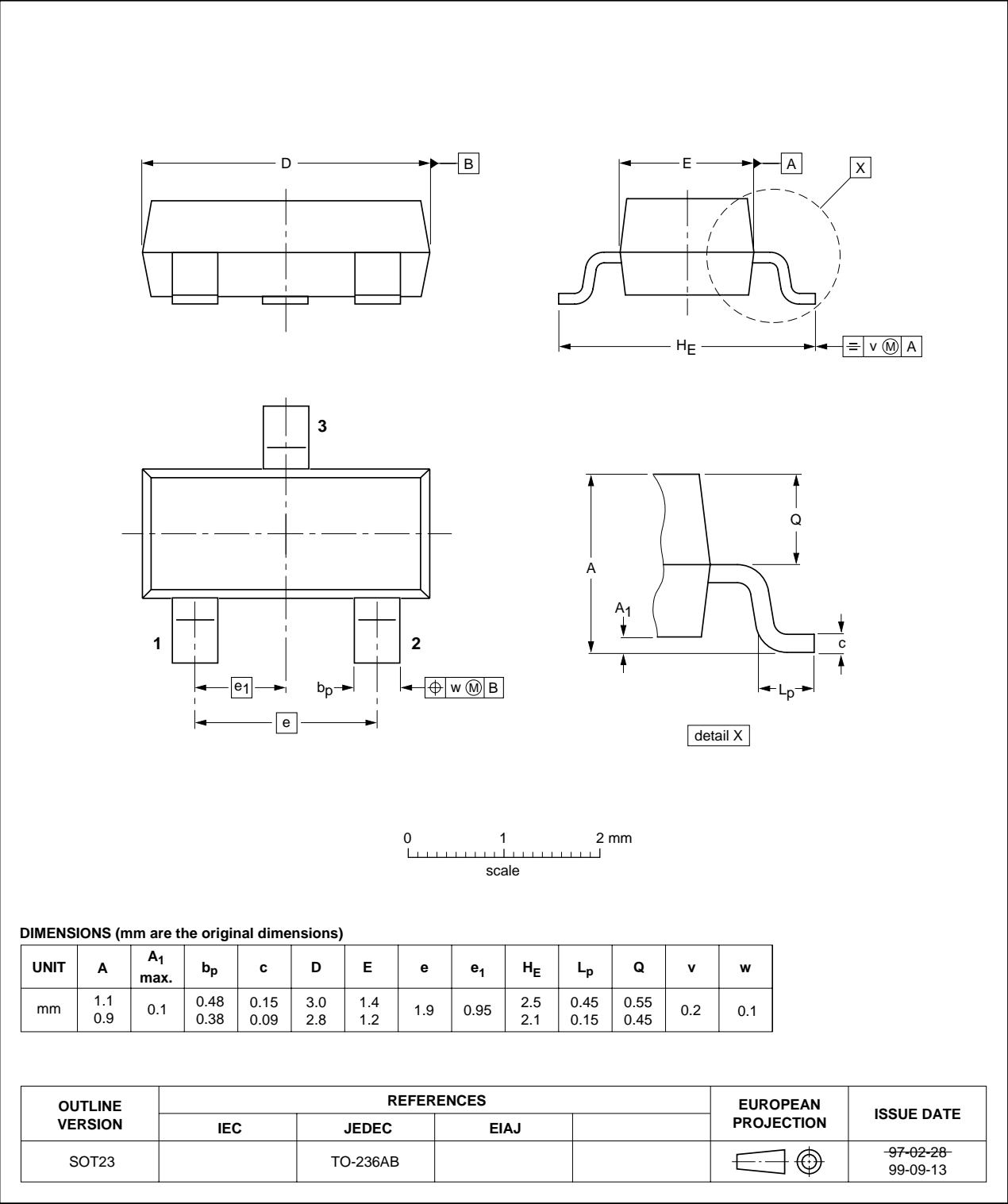


Fig 1. Package outline.

9. Revision history

Table 8: Revision history

Document ID	Release date	Data sheet status	Change notice	Order number	Supersedes
PDTA123YT_2	20040611	Objective data	-	9397 750 13217	PDTA123YT_1
Modifications:	<ul style="list-style-type: none"><li>• <math>C_{c(max)} = 2\text{ pF}</math> (was &lt;tbid&gt;); see <a href="#">Table 7 “Characteristics”</a></li><li>• <math>V_{i(off)(typ)} = -0.75\text{ V}</math> (was &lt;tbid&gt;); see <a href="#">Table 7 “Characteristics”</a></li><li>• <math>V_{i(on)(typ)} = -1.15\text{ V}</math> (was &lt;tbid&gt;); see <a href="#">Table 7 “Characteristics”</a></li></ul>				
PDTA123YT_1	20040325	Objective data	-	9397 750 12549	-

## 10. Data sheet status

Level	Data sheet status <sup>[1]</sup>	Product status <sup>[2] [3]</sup>	Definition
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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III	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

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[3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

## 11. Definitions

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**Limiting values definition** — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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